



**For Immediate Release**

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**AEHR TEST SYSTEMS SCHEDULES SECOND QUARTER  
FISCAL YEAR 2013 EARNINGS RELEASE AND CONFERENCE CALL**

**Fremont, CA (December 20, 2012) - Aehr Test Systems (Nasdaq: AEHR)**, a worldwide supplier of semiconductor test and burn-in equipment, today announced that it will report financial results for the second quarter of fiscal 2013 ended November 30, 2012 after the market closes on Wednesday, January 9, 2013.

Management of Aehr Test Systems will host a conference call and webcast that same day at 5:00 p.m. Eastern (2:00 p.m. Pacific) to discuss the Company's operating performance. The conference call will be accessible live via the internet at [www.aehr.com](http://www.aehr.com). Please go to the website at least 15 minutes before start time to register, download and install any necessary audio software. A replay of the webcast will be available at [www.aehr.com](http://www.aehr.com) for 90 days.

**About Aehr Test Systems**

Headquartered in Fremont, California, Aehr Test Systems is a worldwide provider of test systems for burning-in and testing logic and memory integrated circuits and has an installed base of more than 2,500 systems worldwide. Increased quality and reliability needs of the Automotive and Mobility integrated circuit markets are driving additional test requirements, capacity needs and opportunities for Aehr Test products in package and wafer level test. Aehr Test has developed and introduced several innovative products, including the ABTS™ and FOX™ family of test and burn-in systems and the DiePak® carrier. The ABTS system is used in production and qualification testing of packaged parts for both low-power and high-power logic as well as all common types of memory devices. The FOX system is a full wafer contact test and burn-in system used for burn-in and functional test of complex devices, such as leading-edge memories, digital signal processors, microprocessors, microcontrollers and systems-on-a-chip. The DiePak carrier is a reusable, temporary package that enables IC manufacturers to perform cost-effective final test and burn-in of bare die. For more information, please visit the Company's website at [www.aehr.com](http://www.aehr.com).

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